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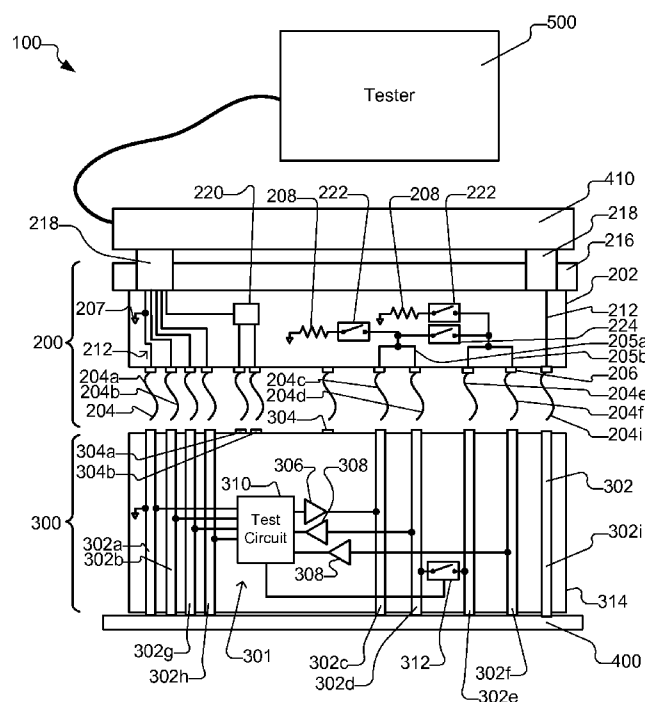
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(54) Title: TESTING TECHNIQUES FOR THROUGH-DEVICE VIAS

Figure 1



(57) Abstract: Techniques for testing an electronic device with through-device vias can include using a probe card assembly with probes for contacting connection structures of the electronic device including ends of through-device vias of the electronic device. A pair of the probes can be electrically connected in the probe card assembly and can thus contact and form a direct return loop from one through-device via to another through-device via of a pair of the through-device vias with which the pair of probes is in contact. The electronic device can include test circuitry for driving a test signal onto the one of the through-device vias and a receiver for detecting the test signal on the other of the through-device vias.



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